

Overvoltage Protection for 2-Series to 4-Series Cell Li-Ion Batteries with External Delay Capacitor

Check for Samples: [bq771600](#), [bq771601](#), [bq771602](#)

FEATURES

- 2-, 3-, and 4-Series Cell Overvoltage Protection
- External Capacitor-Programmed Delay Timer
- Fixed OVP Threshold
- High-Accuracy Overvoltage Protection: ± 10 mV
- Low Power Consumption $I_{CC} = 1 \mu A$ ($V_{CELL(ALL)} < V_{PROTECT}$)
- Low Leakage Current Per Cell Input < 100 nA
- Small Package Footprint
 - 8-pin QFN (3 mm x 4 mm)

APPLICATIONS

- Power Tools
- UPS Battery Backup
- Light Electric Vehicles
 - eBike
 - eScooter
 - Pedal Assist Bicycles

DESCRIPTION

The bq7716xy family of products is an overvoltage monitor and protector for Li-Ion battery pack systems. Each cell is monitored independently for an overvoltage condition.

In the bq7716xy device, an external delay timer is initiated upon detection of an overvoltage condition on any cell. Upon expiration of the delay timer, the output is triggered into its active state (either high or low, depending on the configuration). The external delay timer feature also includes the ability to detect an open or shorted delay capacitor on the CD pin, which will similarly trigger the output driver in an overvoltage condition.

For quicker production-line testing, the bq7716xy device provides a Customer Test Mode with greatly reduced delay time.

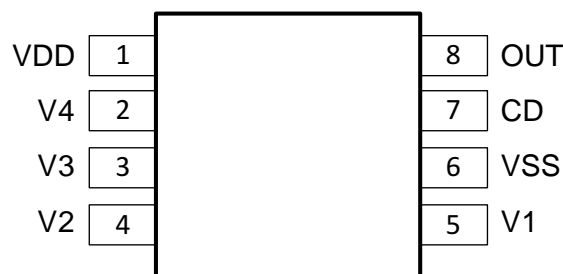


Figure 1. bq7716xy Pinout



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

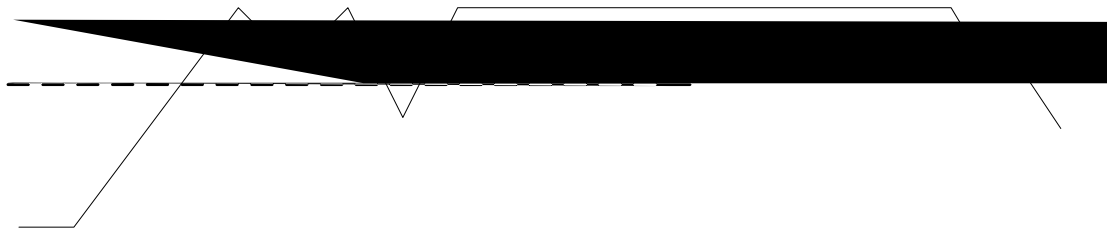
T _A	Part Number	Package	Package Designator	OVP (V)	OV Hysteresis (V)	Output Drive	Tape and Reel (Large)	Tape and Reel (Small)
-40°C to 110°C	bq771600	8-pin QFN	DPJ	4.300	0.300	CMOS Active High	bq771600DPJR	bq771600DPJT
	bq771601			4.225	0.050	CMOS Active High	bq771601DPJR	bq771601DPJT
	bq771602			4.225	0.050	NCH Active Low, Open Drain	bq771602DPJR	bq771602DPJT
	bq771603 ⁽¹⁾			4.325	0.050	NCH Active Low, Open Drain	bq771603DPJR	bq771603DPJT
	bq7716xy ⁽²⁾			3.850–4.650	0–0.300	CMOS Active High or NCH Active Low, Open Drain	bq7716xyTBD	bq7716xyTBD

- (1) Product Preview only
 (2) Future Option, contact TI.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		bq7716xy	UNITS
		8 PINS	
JA	Junction-to-ambient thermal resistance	56.6	°C/W
JC(top)	Junction-to-case(top) thermal resistance	56.4	
JB	Junction-to-board thermal resistance	30.6	
JT	Junction-to-top characterization parameter	1.0	
JB	Junction-to-board characterization parameter	37.8	
JC(bottom)	Junction-to-case(bottom) thermal resistance	11.3	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).



(V4-V3, V3-V2, V2-V1, V1-VSS)

Figure 3 shows the behavior of the CD pin during an OV sequence.

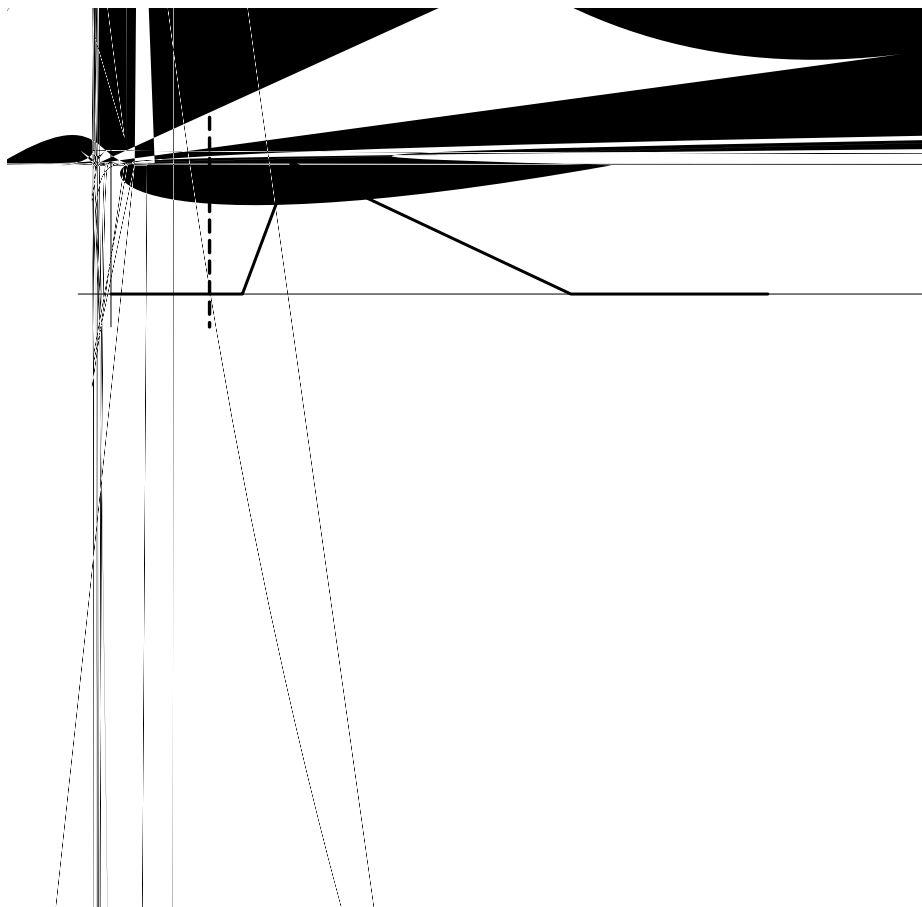


Figure 3. CD Pin Mechanism

Sense Positive Input for Vx

This is an input to sense each single battery cell voltage. A series resistor and a capacitor across the cell for each input is required for noise filtering and stable voltage monitoring.

Output Drive, OUT

This terminal serves as the fault signal output, and may be ordered in either active HIGH or LOW options.

Supply Input, VDD

This terminal is the unregulated input power source for the IC. A series resistor is connected to limit the current, and a capacitor is connected to ground for noise filtering.

External Delay Capacitor, CD

This terminal is connected to an external capacitor that is used for setting the delay timer during an overvoltage fault event.

The CD pin includes a timeout detection circuit to ensure that the output drives active even with a shorted or open capacitor during an overvoltage event.

The capacitor connected on the CD pin rapidly charges to a voltage if any one of the cell inputs exceeds the OV threshold. Then the delay circuit gradually discharges the capacitor on the CD pin. Once this capacitor discharges below a set voltage, the OUT transitions from an inactive to active state.

To calculate the delay, use the following equation:

$$t_{CD} \text{ (sec)} = K * C_{CD} \text{ (}\mu\text{F)}, \text{ where } K = 10 \text{ to } 20 \text{ range.} \tag{1}$$

Example: If $C_{CD} = 0.1 \mu\text{F}$ (typical), then the delay timer range is

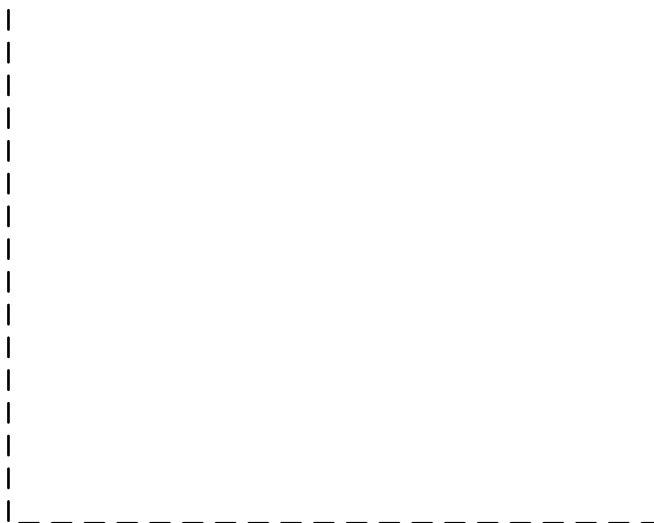
$$t_{CD} \text{ (sec)} = 10 * 0.1 = 1 \text{ s (Minimum)}$$

$$t_{CD} \text{ (sec)} = 20 * 0.1 = 2 \text{ s (Maximum)}$$

NOTE

The tolerance on the capacitor used for C_{CD} increases the range of the t_{CD} timer.

FUNCTIONAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER	CONDITION	VALUE/UNIT
Supply voltage range	VDD–VSS	–0.3 to 30 V
Input voltage range	V4–V3, V3–V2, V2–V1, V1–VSS, or CD–VSS	–0.3 to 30 V
Output voltage range	OUT–VSS	–0.3 to 30 V
Continuous total power dissipation, P _{TOT}		See package dissipation rating.
Functional temperature		–40 to 110 to 110 to

DC CHARACTERISTICS (continued)

Typical values stated where $T_A = 25^\circ\text{C}$ and $V_{DD} = 14.4\text{ V}$, MIN/MAX values stated where $T_A = -40^\circ\text{C}$ to 110°C and $V_{DD} = 3\text{ V}$ to 20 V (unless otherwise noted).

SYMBOL	PARAMETER	CONDITION	MIN	TYP	MAX	UNIT
Delay Timer						
t_{CD}	OV Delay Time	$C_{CD} = 0.1\ \mu\text{F}$ (For capacitor sizing, see PIN DETAILS.)	1	1.5	2	s
V_{CD}	CD Fault Detection External Comparator Threshold, Initial Charge Value	The CD pin will first be quickly charged to this value before being discharged back to VSS.		1.5		V
$t_{CHGDELAY}$	CD Charging Delay	OVP to OUT delay with CD shorted to ground	20		170	ms
I_{CHG}	OV Detection Charging Current	CD pin fast charging current from VSS to V_{CD} to begin delay countdown		300		μA
I_{DSG}	OV Detection Discharging Current	CD pin discharging current from V_{DELAY} to VSS		100		nA

TYPICAL CHARACTERISTICS

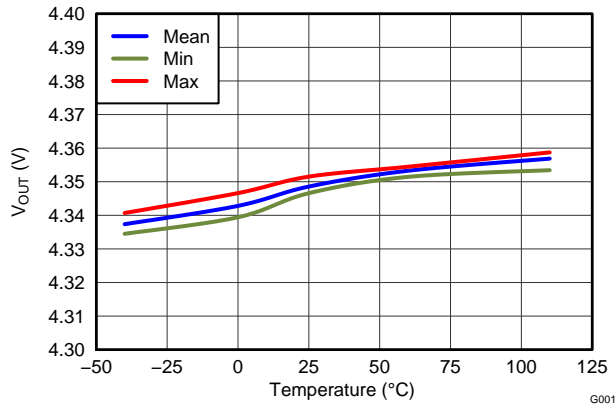


Figure 4. Overtolerance Threshold (OVT) vs. Temperature

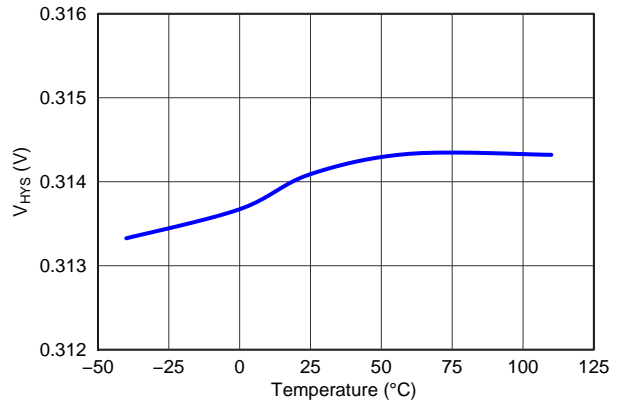


Figure 5. Hysteresis V_{HYS} vs. Temperature

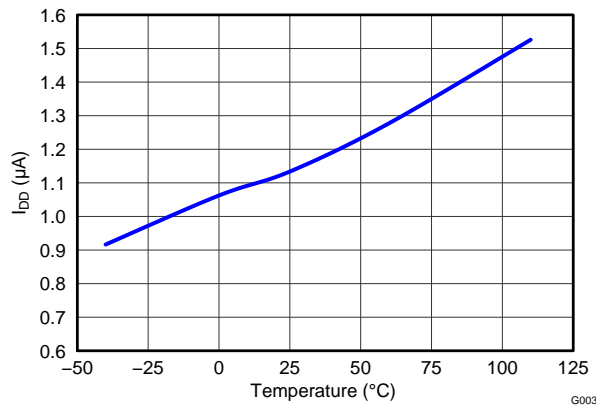


Figure 6. I_{DD} Current Consumption vs. Temperature at $V_{DD} = 16\text{ V}$

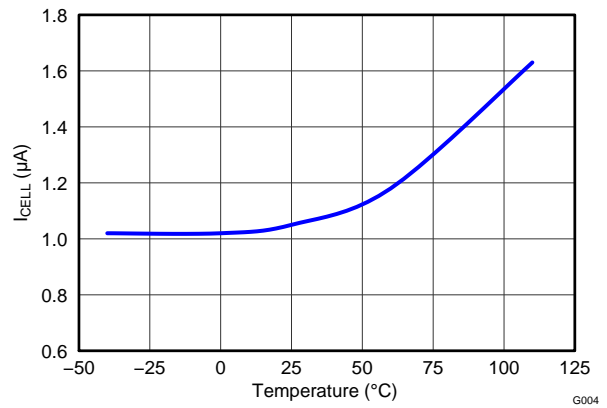


Figure 7. I_{CELL} vs. Temperature at $V_{CELL} = 9.2\text{ V}$

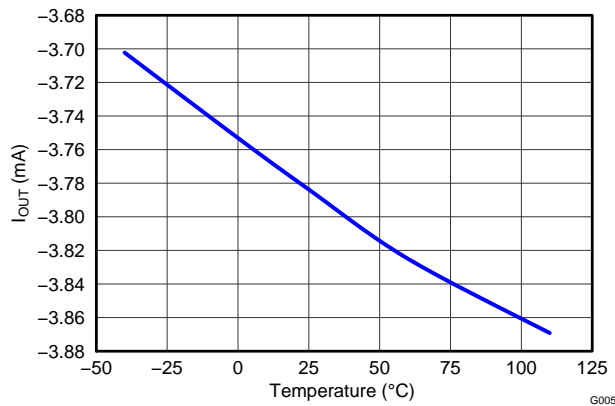


Figure 8. Output Current I_{OUT} vs. Temperature

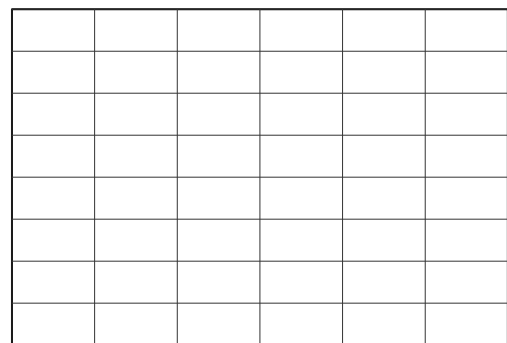


Figure 9. V_{OUT} vs. V_{DD}

APPLICATION SCHEMATIC

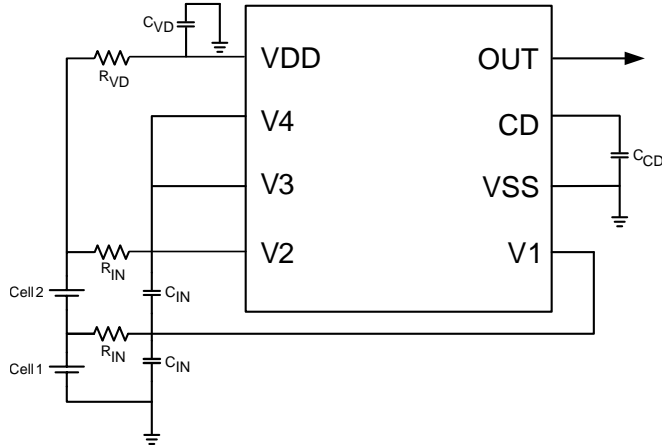


Figure 11. 2-Series Cell Configuration with Capacitor-Programmed Delay

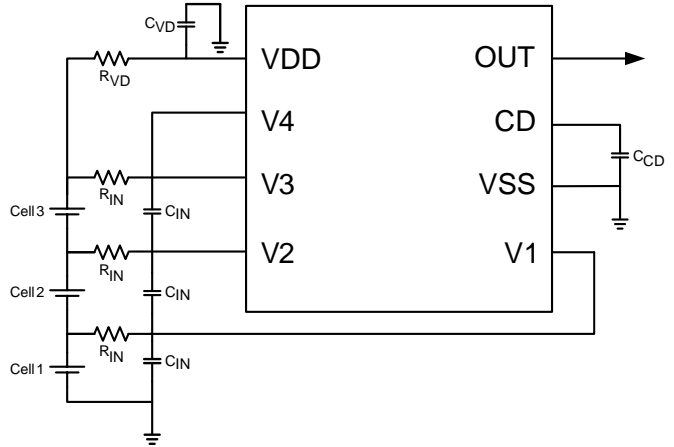


Figure 12. 3-Series Cell Configuration with Capacitor-Programmed Delay

NOTE

In these application examples of 2s and 3s, an external pull-up resistor is required on the OUT terminal to configure for an Open Drain Active Low operation.

Figure 14 shows the measurement for current consumption for the product for both VDD and Vx.

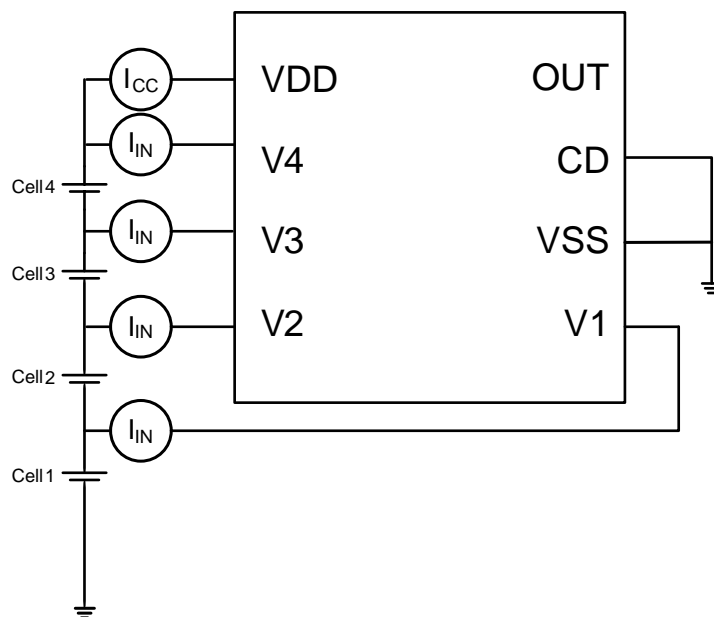


Figure 14. Configuration for IC Current Consumption Test

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
BQ771600DPJR	ACTIVE	WSON	DPJ	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
BQ771600DPJT	ACTIVE	WSON	DPJ	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
BQ771601DPJR	ACTIVE	WSON	DPJ	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
BQ771601DPJT	ACTIVE	WSON	DPJ	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
BQ771602DPJR	ACTIVE	WSON	DPJ	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
BQ771602DPJT	ACTIVE	WSON	DPJ	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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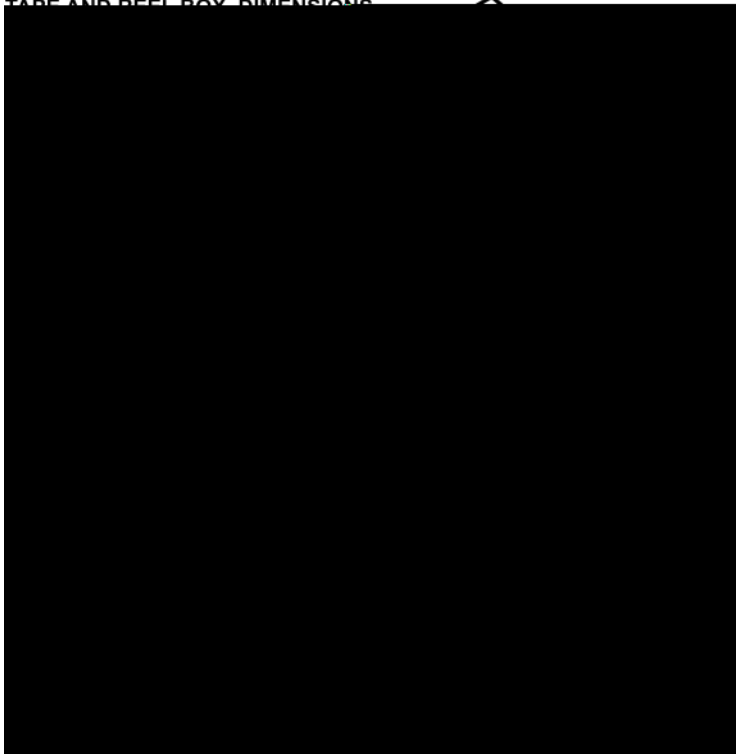
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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ771600DPJR	WSON	DPJ	8	3000	330.0	12.4	3.3	4.3	1.1	8.0	12.0	Q2
BQ771600DPJT	WSON	DPJ	8	250	180.0	12.4	3.3	4.3	1.1	8.0	12.0	Q2
BQ771601DPJR	WSON	DPJ	8	3000	330.0	12.4	3.3					

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ771600DPJR	WSON	DPJ	8	3000	367.0	367.0	35.0
BQ771600DPJT	WSON	DPJ	8	250	210.0	185.0	35.0
BQ771601DPJR	WSON	DPJ	8	3000	367.0	367.0	35.0
BQ771601DPJT	WSON	DPJ	8	250	210.0	185.0	35.0
BQ771602DPJR	WSON	DPJ	8	3000	367.0	367.0	35.0
BQ771602DPJT	WSON	DPJ	8	250	210.0	185.0	35.0

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